

		ATTY. DOCKET NO.:	APPLICATION NO.:
		81421-4038	
		APPLICANT:	
		Steen Ørsted ANDERSEN	
		FILING DATE:	GROUP:
		March 9, 2004	

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
SDI	AA	6,240,933 B1	6/2001	Bergman	134	1.3	
	AB	6,312,797	11/2001	Yokokawa et al.	428	336	
	AC	2002/0062841	5/2002	Twu et al.	134	3	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES
	AE						
	AF						
	AG						
	AH						
	AI						

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

SDI	AJ	Seiji Fujino et al., "Silicon Wafer Direct Bonding through the Amorphous Layer", Jp.n.. J. Appl. Phys., Vol. 34, pp. 1322-1324 (1995)
	AK	
	AL	
	AM	
	AN	
	AO	

EXAMINER

DATE CONSIDERED

6/7/08

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				ATTY. DOCKET NO.:	APPLICATION NO.:	
				4717-10500	10/808,288	
				APPLICANT:		
				C. Maleville et al.		
				FILING DATE:	GROUP:	
				March 25, 2004	2812	

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
SDI	AA	2002/0020436 A1	2/2002	Bergman	134	30	
	AB						
	AC						
	AD						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES
SDS	AB	EP 0971 396 A1	1/2000	Europe			X
	AF						
	AG						
	AH						
	AI						

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

AJ)	
AK		
AL		
AM		
AN		
AO		

EXAMINER	DATE CONSIDERED
<i>Shanette Boar</i>	6/7/05

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